



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Gregory E. Howard

Art Unit: 2824

Serial No.: 10/739,418

Examiner: TBD

Filed: 12/18/03

Docket: TI-35903

For: Flexible Package with Rigid Substrate Segments for High Density Integrated  
Circuit Systems

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that the above correspondence is being deposited  
with the U.S. Postal Service on 4-13-04 as  
First Class Mail in an envelope addressed to: Commissioner for  
Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Karen Vertz  
Karen Vertz

4-13-04  
Date

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Enclosed are **EIGHT (8)** sheets of formal drawings for the above-referenced case.  
Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments  
Incorporated. This sheet is enclosed in triplicate.

Respectfully submitted,

Gary C. Honeycutt  
Reg. No. 20,250

Texas Instruments Incorporated  
P.O. Box 655474 M/S 3999  
Dallas, Texas 75265